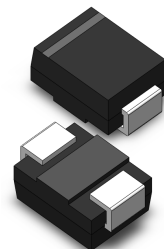


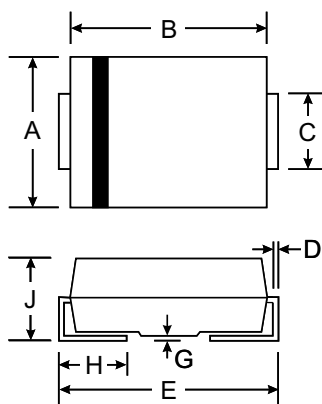
Features

- 50A Peak Pulse Current @ 10/1000 s
- 250A Peak Pulse Current @ 8/20 s
- 58 - 320V Stand-Off Voltages
- Oxide-Glass Passivated Junction
- Bi-Directional Protection In a Single Device
- High Off-State impedance and Low On-State Voltage



Mechanical Data

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)



| SMB(DO-214AA) | | |
|----------------------|------|------|
| Dim | Min | Max |
| A | 3.30 | 3.94 |
| B | 4.06 | 4.70 |
| C | 1.91 | 2.21 |
| D | 0.15 | 0.31 |
| E | 5.00 | 5.59 |
| G | 0.10 | 0.20 |
| H | 0.76 | 1.52 |
| J | 2.00 | 2.62 |
| All Dimensions in mm | | |

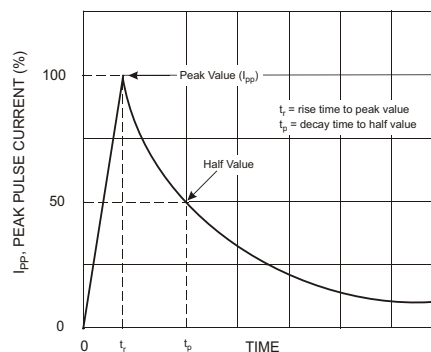
Maximum Ratings @ T_A = 25 C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|--|---------------------|-------------|------|
| Non-Repetitive Peak Impulse Current @ 10/1000us | I _{pp} | 50 | A |
| Non-Repetitive Peak On-State Current @ 8.3ms (one-half cycle) | I _{TSM} | 30 | A |
| Junction Temperature Range | T _j | -40 to +150 | C |
| Storage Temperature Range | T _{STG} | -55 to +150 | C |
| Thermal Resistance, Junction to Lead | R _{JL} | 20 | °C/W |
| Thermal Resistance, Junction to Ambient | R _{JA} | 100 | °C/W |
| Typical Positive Temperature Coefficient for Breakdown Voltage | VBR/ T _j | 0.1 | %/°C |

Maximum Rated Surge Waveform

| Waveform | Standard | I _{pp} (A) |
|------------|----------------|---------------------|
| 2/10 us | GR-1089-CORE | 300 |
| 8/20 us | IEC 61000-4-5 | 250 |
| 10/160 us | FCC Part 68 | 150 |
| 10/700 us | ITU-T, K20/K21 | 100 |
| 10/560 us | FCC Part 68 | 75 |
| 10/1000 us | GR-1089-CORE | 50 |



Electrical Characteristics @ $T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified

| Part Number | Marking Code | Rated Repetitive Off-State Voltage | Off-State Leakage Current @ V_{DRM} | Breakover Voltage | On-State Voltage @ $I_T = 1\text{A}$ | Breakover Current I_{BO} | | Holding Current I_H | | Off-State Capacitance |
|-------------|--------------|------------------------------------|---------------------------------------|-------------------|--------------------------------------|----------------------------|----------|-----------------------|----------|-----------------------|
| | | V_{DRM} (V) | I_{DRM} (μA) | V_{BO} (V) | V_T (V) | Min (mA) | Max (mA) | Min (mA) | Max (mA) | C_O (pF) |
| TB0640M | T064M | 58 | 5 | 77 | 3.5 | 50 | 800 | 150 | 800 | 140 |
| TB0720M | T072M | 65 | 5 | 88 | 3.5 | 50 | 800 | 150 | 800 | 140 |
| TB0900M | T090M | 75 | 5 | 98 | 3.5 | 50 | 800 | 150 | 800 | 140 |
| TB1100M | T110M | 90 | 5 | 130 | 3.5 | 50 | 800 | 150 | 800 | 90 |
| TB1300M | T130M | 120 | 5 | 160 | 3.5 | 50 | 800 | 150 | 800 | 90 |
| TB1500M | T150M | 140 | 5 | 180 | 3.5 | 50 | 800 | 150 | 800 | 90 |
| TB1800M | T180M | 160 | 5 | 220 | 3.5 | 50 | 800 | 150 | 800 | 90 |
| TB2300M | T230M | 190 | 5 | 265 | 3.5 | 50 | 800 | 150 | 800 | 60 |
| TB2600M | T260M | 220 | 5 | 300 | 3.5 | 50 | 800 | 150 | 800 | 60 |
| TB3100M | T310M | 275 | 5 | 350 | 3.5 | 50 | 800 | 150 | 800 | 60 |
| TB3500M | T350M | 320 | 5 | 400 | 3.5 | 50 | 800 | 150 | 800 | 60 |

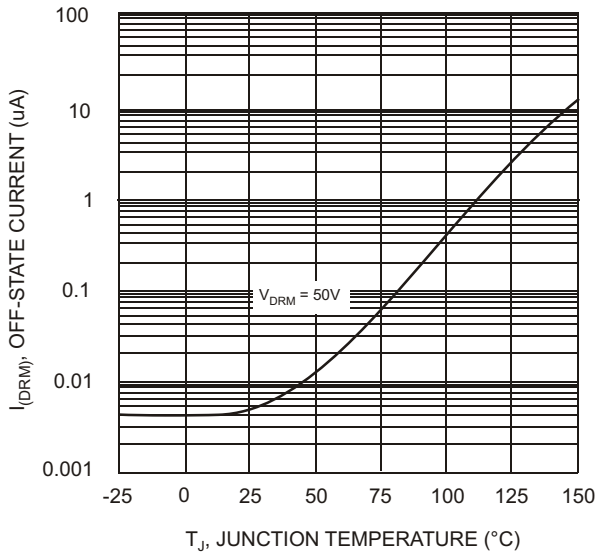


Fig. 1 Off-State Current vs. Junction Temperature

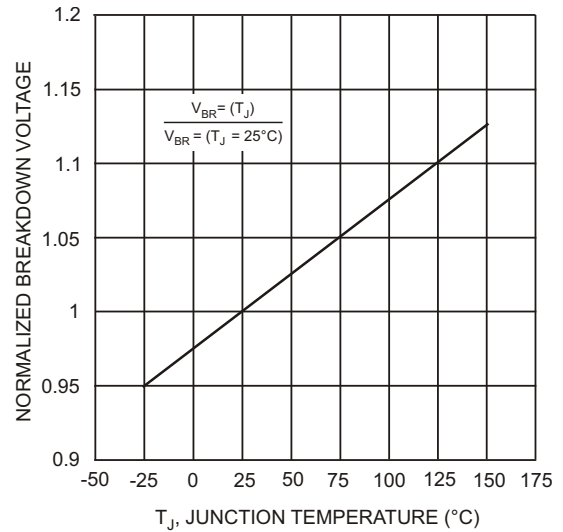


Fig. 2 Relative Variation of Breakdown Voltage vs. Junction Temperature

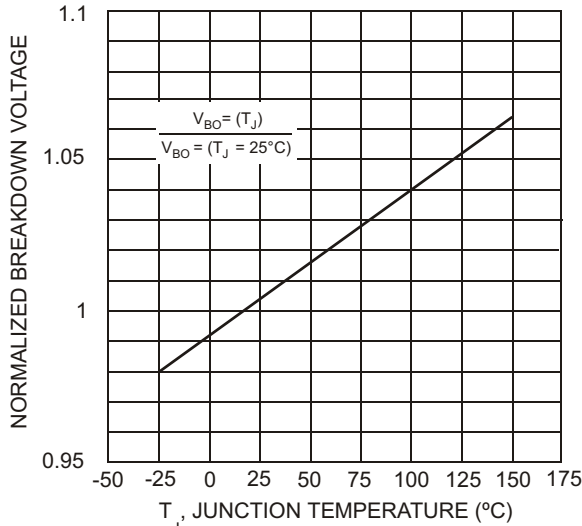


Fig. 3 Relative Variation of Breakover Voltage vs. Junction Temperature

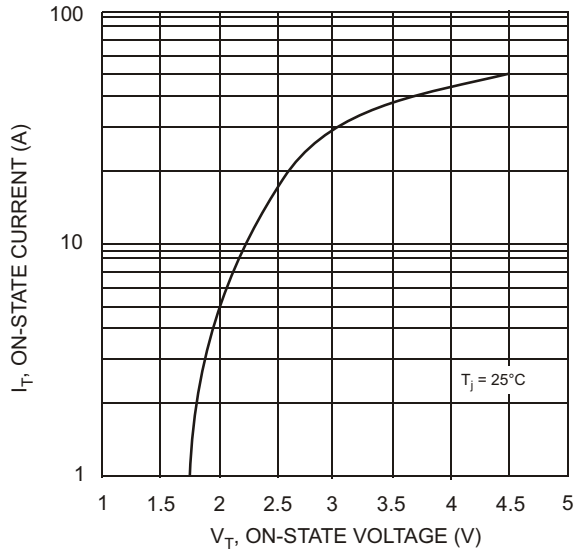


Fig. 4 On-State Current vs. On-State Voltage

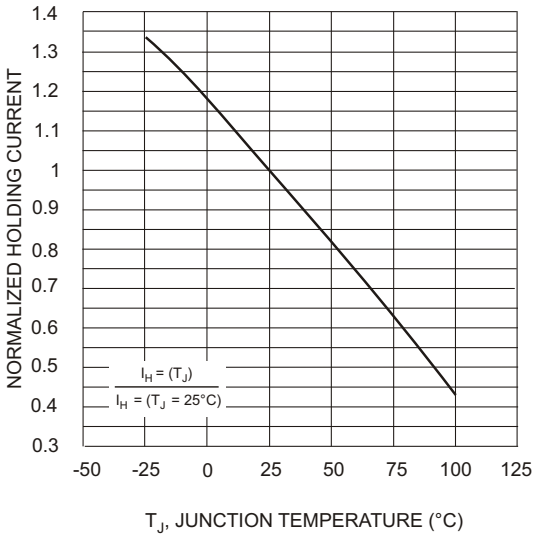


Fig. 5 Relative Variation of Holding Current vs. Junction Temperature

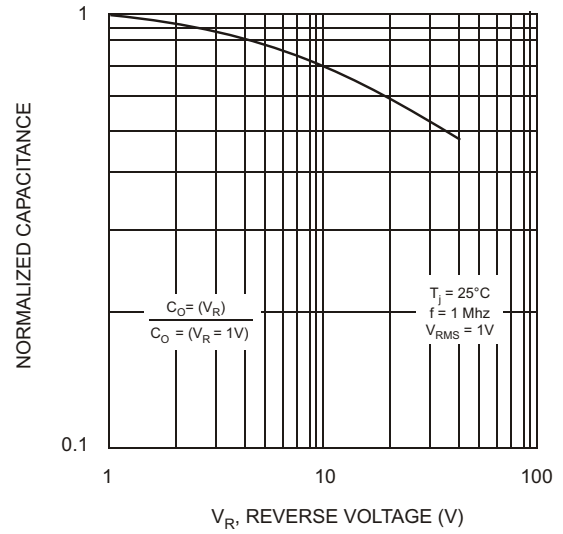


Fig. 6 Relative Variation of Junction Capacitance vs. Reverse Voltage Bias